

/ Descriptions

WR0<5+U, M M E QSQ Æ M y s ll 1 Silicon NPN transistor in a TO-92(R) Plastic Package.

/ Features

$$\alpha \in \mathbb{R} \mid \mathbb{H} \cong \phi$$

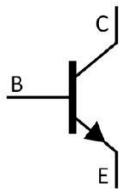
High Voltage, Low Noise.

/ Applications

$$\tilde{\mathbf{f}}_i^{\text{new}} = \tilde{\mathbf{f}}_i + \frac{\tilde{\mathbf{f}}_i^T \tilde{\mathbf{f}}_i}{\tilde{\mathbf{f}}_i^T \tilde{\mathbf{f}}_i} \tilde{\mathbf{f}}_i$$

General purpose and switching application.

/ Equivalent Circuit



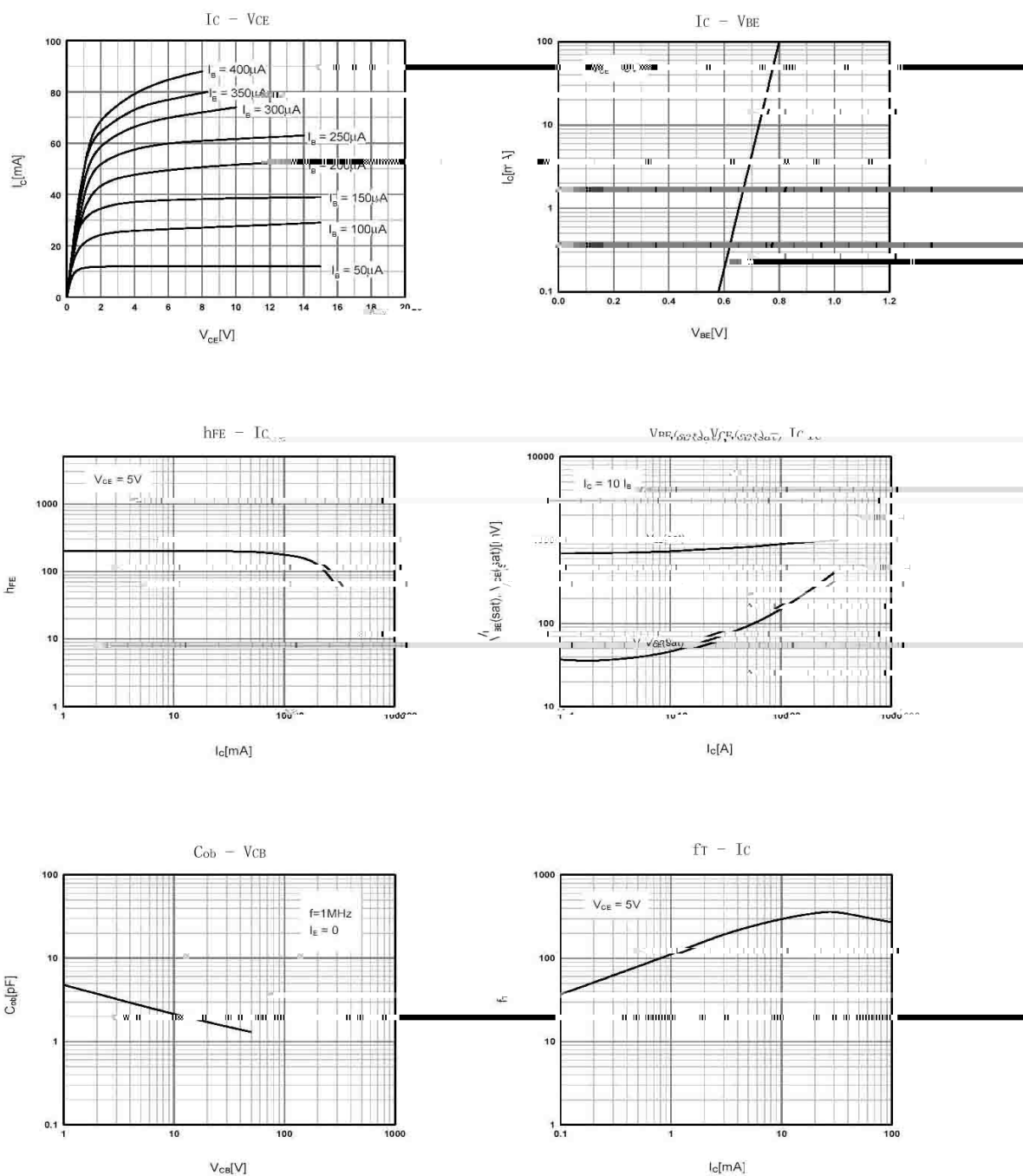
/ Pinning

PIN1 χ EmitterPIN 2 χ BasePIN 3 χ Collector

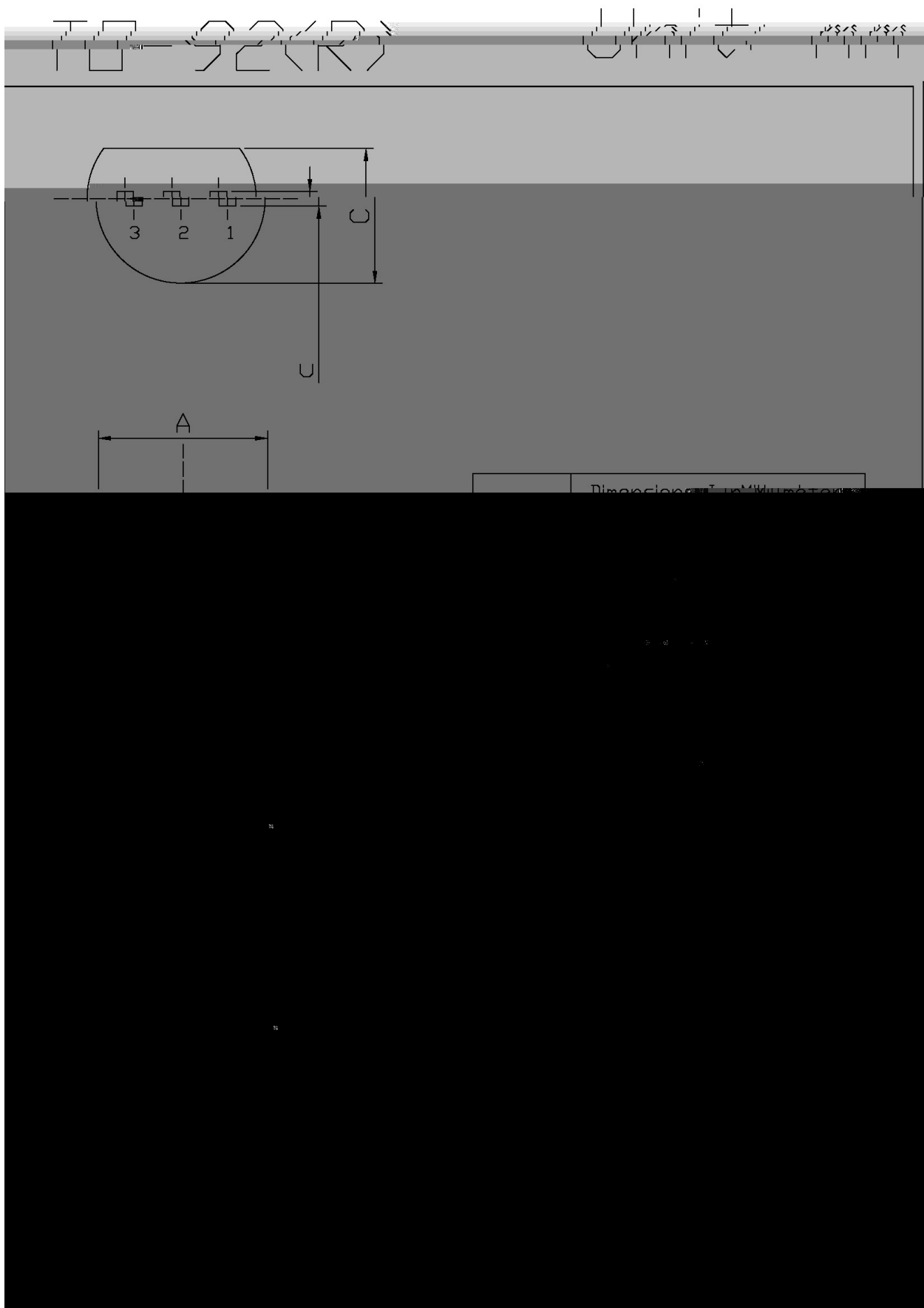
/ h_{FE} Classifications & Marking

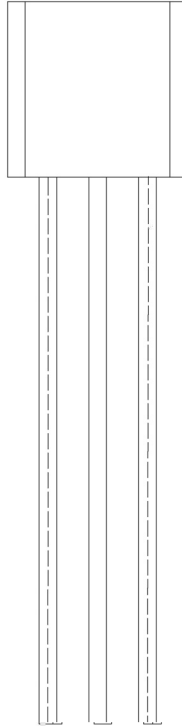
h _{FE} Classifications	A	B	C
Symbol			
h _{FE} Range			

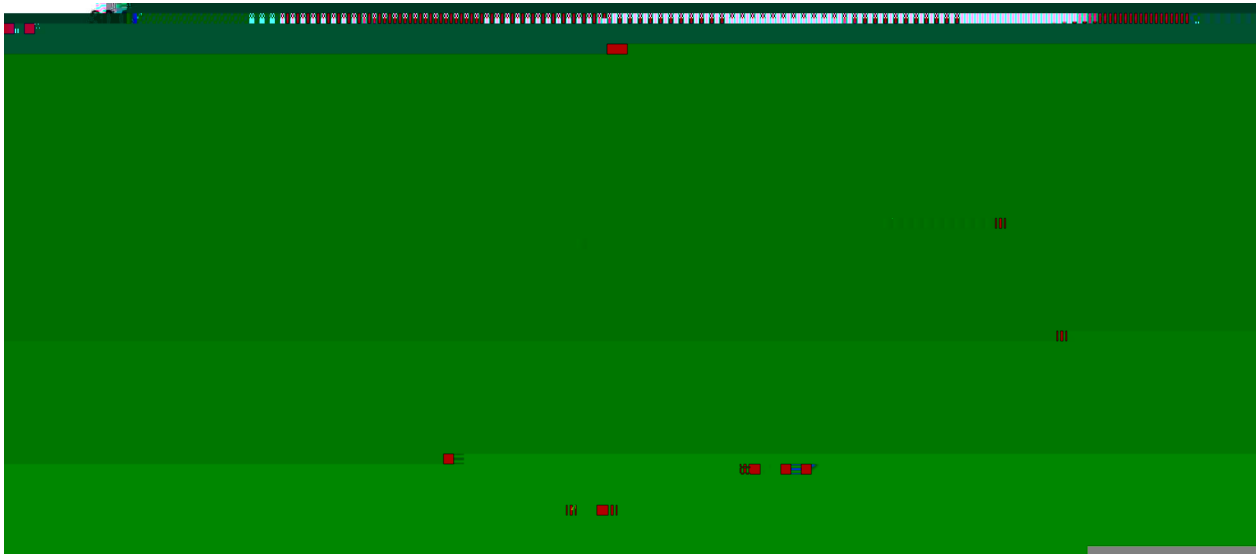
/ Electrical Characteristic Curve



/ Package Dimensions






() / Temperature Profile for Dip Soldering(Pb-Free)


б " X

1. 1. 25~150 °C, Time: 60~90sec;

2. 2. 255 °C, Duration: 5 ° 0.5sec;

3. 3. Cooling Speed: 2~10 °C /sec.

Note:

1.Preheating:25~150 °C , Time:60~90sec.

2.Peak Temp.:255 °C , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 °C /sec.

/ Resistance to Soldering Heat Test Conditions

□ °C 270 ± 5

°C 10 ± 1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

°C 10 ± 1 sec. / BULK

Package Type	Units					Dimension		(unit mm3)

°C 10 ± 1 sec. / AMMO

Package Type	Units					Dimension		(unit mm3)

/ Notices